RoboClock®, CY7B9950

2.5/3.3V, 200 MHz High-Speed Multi-Phase PLL Clock Buffer

Features

- 2.5V or 3.3V operation
- Split output bank power supplies
- Output frequency range: 6 MHz to 200 MHz
- 50 ps typical matched-pair Output-output skew
- 50 ps typical Cycle-cycle jitter
- 49.5/50.5% typical output duty cycle
- Selectable output drive strength
- Selectable positive or negative edge synchronization
- Eight LVTTL outputs driving 50 Ω terminated lines
- LVCMOS/LVTTL over-voltage-tolerant reference input
- Phase adjustments in 625-/1250-ps steps up to ±7.5 ns
- 2x, 4x multiply and (1/2)x, (1/4)x divide ratios
- Spread-Spectrum compatible
- Industrial temp. range: –40°C to +85°C
- 32-pin TQFP package

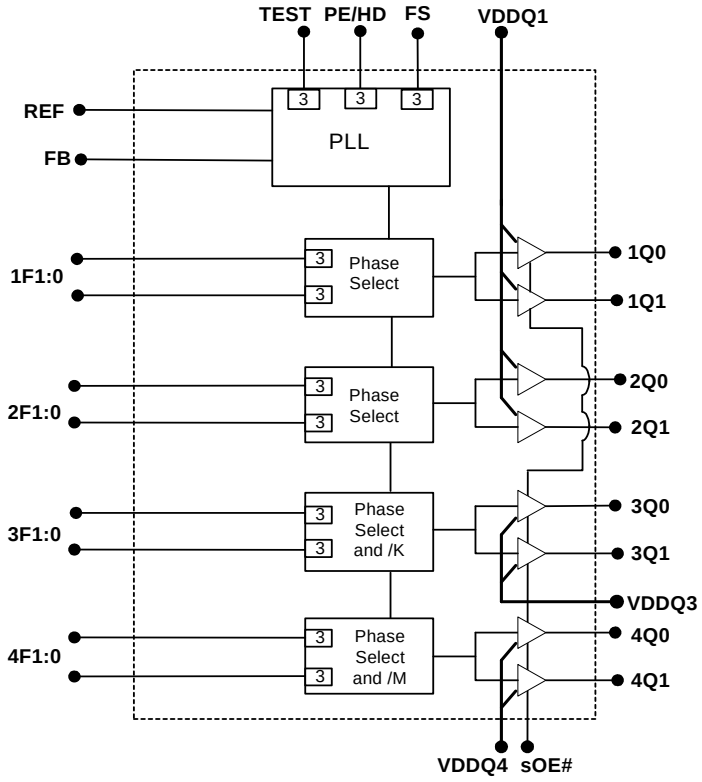
Description

The CY7B9950 RoboClock® is a low voltage, low power, eight-output, 200 MHz clock driver. It features output phase programmability which is necessary to optimize the timing of high performance computer and communication systems.

The user can program the phase of the output banks through nF[0:1] pins. The adjustable phase feature allows the user to skew the outputs to lead or lag the reference clock. Any one of the outputs can be connected to the feedback input to achieve different reference frequency multiplications, and divide ratios and zero input-output delay.

The device also features split output bank power supplies, which enable the user to run two banks (1Qn and 2Qn) at a power supply level different from that of the other two banks (3Qn and 4Qn). Additionally, the three-level PE/HD pin controls the synchronization of the output signals to either the rising, or the falling edge of the reference clock and selects the drive strength of the output buffers. The high drive option (PE/HD = MID) increases the output current from ± 12 mA to ± 24 mA(3.3V).

Logic Block Diagram



Pinouts

Figure 1. Pin Diagram - 32 Pin TQFP package Top view

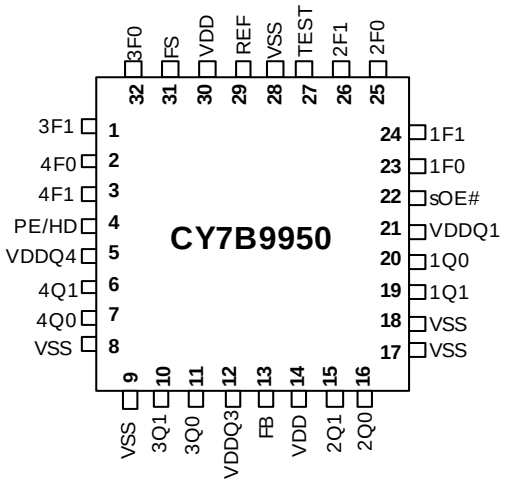


Table 1. Pin Definitions

Pin	Name	IO[1]	Type	Description
29	REF	I	LVTTL/LVCMOS	**Reference Clock Input.**
13	FB	I	LVTTL	**Feedback Input.**
27	TEST	I	Three-level	**When MID or HIGH, disables Phase-locked Loop (PLL)**[3]. REF goes to outputs of Bank 1 and Bank 2. REF also goes to outputs of Bank 3 and Bank 4 through output dividers K and M. Set LOW for normal operation.
22	sOE#	I, PD	Two-level	**Synchronous Output Enable**. When HIGH, it stops clock outputs (except 2Q0 and 2Q1) in a LOW state (for PE = H or M) – 2Q0, and 2Q1 may be used as the feedback signal to maintain phase lock. When TEST is held at MID level and sOE# is HIGH, the nF[1:0] pins act as output disable controls for individual banks when nF[1:0] = LL. Set sOE# LOW for normal operation.
4	PE/HD	I, PU	Three-level	**Selects Positive or Negative Edge Control and High or Low Output Drive Strength**. When LOW/HIGH the outputs are synchronized with the negative/positive edge of the reference clock, respectively. When at MID level, the output drive strength is increased and the outputs synchronize with the positive edge of the reference clock (see Table 7 on page 4).
24, 23, 26, 25, 1, 32, 3, 2	nF[1:0]	I	Three-level	**Select Frequency and Phase of the Outputs** (see Table 2, Table 3, Table 4 on page 4, Table 5 on page 4, and Table 6 on page 4).
31	FS	I	Three-level	**Selects VCO Operating Frequency Range** (see Table 5 on page 4)
19, 20, 15, 16, 10, 11, 6, 7	nQ[1:0]	O	LVTTL	**Four Banks of Two Outputs** (see Table 2, Table 3, and Table 4 on page 4)
21	V_{DDQ1}[2]	PWR	Power	**Power Supply for Bank 1 and Bank 2 Output Buffers** (see Table 8 on page 4 for supply level constraints).
12	V_{DDQ3}[2]	PWR	Power	**Power Supply for Bank 3 Output Buffers** (see Table 8 on page 4 for supply level constraints).
5	V_{DDQ4}[2]	PWR	Power	**Power Supply for Bank 4 Output Buffers** (see Table 8 on page 4 for supply level constraints).
14,30	V_{DD}[2]	PWR	Power	**Power Supply for Internal Circuitry** (see Table 8 on page 4 for supply level constraints).
8,9,17,18,28	V_{SS}	PWR	Power	**Ground**

Device Configuration

The outputs of the CY7B9950 can be configured to run at frequencies ranging from 6 to 200 MHz. Banks 3 and 4 output dividers are controlled by 3F[1:0] and 4F[1:0] as indicated in Table 2 and Table 3, respectively.

Table 2. Output Divider Settings — Bank 3

3F[1:0]	K — Bank3 Output Divider
LL	2
HH	4
Other[4]	1

Table 3. Output Divider Settings — Bank 4

4F[1:0]	M — Bank4 Output Divider
LL	2
Other[4]	1

The three-level FS control pin setting determines the nominal operating frequency range of the divide-by-one outputs of the device. The CY7B9950 PLL operating frequency range that corresponds to each FS level is given in Table 4 on page 4.

Notes
1. "PD" indicates an internal pull-down and "PU" indicates an internal pull-up. "3" indicates a three-level input buffer
2. A bypass capacitor (0.1µF) must be placed as close as possible to each positive power pin (< 0.2"). If these bypass capacitors are not close to the pins their high-frequency filtering characteristic are cancelled by the lead inductance of the traces.
3. When TEST = MID and sOE# = HIGH, PLL remains active with nF[1:0] = LL functioning as an output disable control for individual output banks. Skew selections remain in effect unless nF[1:0] = LL.
4. These states are used to program the phase of the respective banks (see Table 6 on page 4).

Table 4. Frequency Range Select

FS	PLL Frequency Range
L	24 to 50 MHz
M	48 to 100 MHz
H	96 to 200 MHz

The selectable output skew is in discrete increments of time units (t_U).The value of t_U is determined by the FS setting and the maximum nominal frequency. The equation used to determine the t_U value is: $t_U = 1 / (f_{NOM} \times MF)$, where MF is a multiplication factor, which is determined by the FS setting as indicated in Table 5.

Table 5. MF Calculation

FS	MF	f_{NOM} at which t_U is 1.0 ns(MHz)
L	32	31.25
M	16	62.5
H	8	125

Table 6. Output Skew Settings

nF[1:0]	Skew (1Q[0:1],2Q[0:1])	Skew (3Q[0:1])	Skew (4Q[0:1])
LL[5]	$-4t_U$	Divide By 2	Divide By 2
LM	$-3t_U$	$-6t_U$	$v6t_U$
LH	$-2t_U$	$-4t_U$	$-4t_U$
ML	$-1t_U$	$-2t_U$	$v2t_U$
MM	Zero Skew	Zero Skew	Zero Skew
MH	$+1t_U$	$+2t_U$	$+2t_U$
HL	$+2t_U$	$+4t_U$	$+4t_U$
HM	$+3t_U$	$+6t_U$	$+6t_U$
HH	$+4t_U$	Divide By 4	Inverted[6]

In addition to determining whether the outputs synchronize to the rising or the falling edge of the reference signal, the 3-level PE/HD pin controls the output buffer drive strength as indicated in Table 7.

The CY7B9950 features split power supply buses for Banks 1 and 2, Bank 3 and Bank 4, which enables the user to obtain both 3.3V and 2.5V output signals from one device. The core power supply (VDD) must be set a level that is equal or higher than on any one of the output power supplies.

Table 7. PE/HD Settings

PE/HD	Synchronization	Output Drive Strength[7]
L	Negative	Low Drive
M	Positive	High Drive
H	Positive	Low Drive

Table 8. Power Supply Constraints

V_{DD}	V_{DDQ1}[8]	V_{DDQ3}[8]	V_{DDQ4}[8]
3.3V	3.3V or 2.5V	3.3V or 2.5V	3.3V or 2.5V
2.5V	2.5V	2.5V	2.5V

Governing Agencies

The following agencies provide specifications that apply to the CY7B9950. The agency name and relevant specification is listed below.

Table 9. Governing Agencies and Specifications

Agency Name	Specification
JEDEC	JESD 51 (Theta JA) JESD 65 (Skew, Jitter)
IEEE	1596.3 (Jitter Specs)
UL-194_V0	94 (Moisture Grading)
MIL	883E Method 1012.1 (Therma Theta JC)

Notes:
5. LL disables outputs if TEST = MID and sOE# = HIGH.
6. When 4Q[0:1] are set to run inverted (HH mode), sOE# disables these outputs HIGH when PE/HD = HIGH or MID and sOE# disables them LOW when PE/HD = LOW.
7. Please refer to “DC Parameters” section for I_{OH}/I_{OL} specifications.
8. $V_{DDQ1/3/4}$ must not be set at a level higher than that of V_{DD}. They can be set at different levels from each other, e.g., V_{DD} = 3.3V, V_{DDQ1} = 3.3V, V_{DDQ3} = 2.5V and V_{DDQ4} = 2.5V.

Absolute Maximum Conditions

Parameter	Description	Condition	Min	Max	Unit
V_{DD}	Operating Voltage	Functional @ 2.5V ± 5%	2.375	2.625	V
V_{DD}	Operating Voltage	Functional @ 3.3V ± 10%	2.97	3.63	V
$V_{IN(MIN)}$	Input Voltage	Relative to V_{SS}	V_{SS} – 0.3	–	V
$V_{IN(MAX)}$	Input Voltage	Relative to V_{DD}	–	V_{DD} + 0.3	V
T_S	Temperature, Storage	Non-functional	–65	+150	°C
T_A	Temperature, Operating Ambient	Functional	–40	+85	°C
T_J	Temperature, Junction	Functional	–	155	°C
$Ø_{JC}$	Dissipation, Junction to Case	Mil-Spec 883E Method 1012.1	–	42	°C/W
$Ø_{JA}$	Dissipation, Junction to Ambient	JEDEC (JESD 51)	–	105	°C/W
ESD_{HBM}	ESD Protection (Human Body Model)	MIL-STD-883, Method 3015	2000	–	V
UL-94	Flammability Rating	At 1/8 in.	V–0		
MSL	Moisture Sensitivity Level		1		
F_{IT}	Failure in Time	Manufacturing Testing	10		ppm

DC Electrical Specifications at 2.5V

Parameter	Description	Condition		Min	Max	Unit
V_{DD}	2.5 Operating Voltage	2.5V ± 5%		2.375	2.625	V
V_{IL}	Input LOW Voltage	REF, FB and sOE# Inputs		–	0.7	V
V_{IH}	Input HIGH Voltage			1.7	–	V
V_{IHH}[9]	Input HIGH Voltage	3-Level Inputs (TEST, FS, nF[1:0], PE/HD) (These pins are normally wired to V_{DD}, GND or unconnected.)		V_{DD} – 0.4	–	V
V_{IMM}[9]	Input MID Voltage			$V_{DD}/2$ – 0.2	$V_{DD}/2$ + 0.2	V
V_{ILL}[9]	Input LOW Voltage			–	0.4	V
I_{IL}	Input Leakage Current	$V_{IN} = V_{DD}/G_{ND}$, V_{DD} = max. (REF and FB inputs)		–5	5	µA
I_3	3-Level Input DC Current	HIGH, $V_{IN} = V_{DD}$	3-Level Inputs (TEST, FS, nF[1:0], DS[1:0], PD#/DIV, PE/HD)	–	200	µA
		MID, $V_{IN} = V_{DD}/2$		–50	50	µA
		LOW, $V_{IN} = V_{SS}$		–200	–	µA
I_{PU}	Input Pull-up Current	$V_{IN} = V_{SS}$, V_{DD} = max.		–25	–	µA
I_{PD}	Input Pull-down Current	$V_{IN} = V_{DD}$, V_{DD} = max., (sOE#)		–	100	µA
V_{OL}	Output LOW Voltage	I_{OL} = 12 mA (PE/HD = L/H), (nQ[0:1])		–	0.4	V
		I_{OL} = 20 mA (PE/HD = MID), (nQ[0:1])		–	0.4	V
V_{OH}	Output HIGH Voltage	I_{OH} = –12 mA (PE/HD = L/H), (nQ[0:1])		2.0	–	V
		I_{OH} = –20 mA (PE/HD = MID), (nQ[0:1])		2.0	–	V
I_{DDQ}	Quiescent Supply Current	V_{DD} = max., TEST = MID, REF = LOW, sOE# = LOW, outputs not loaded		–	2	mA
I_{DD}	Dynamic Supply Current	At 100 MHz		150		mA
C_{IN}	Input Pin Capacitance			4		pF

Note
9. These inputs are normally wired to V_{DD}, GND or unconnected. Internal termination resistors bias unconnected inputs to $V_{DD}/2$.

DC Specifications at 3.3V

Parameter	Description	Condition		Min	Max	Unit
V_{DD}	3.3 Operating Voltage	3.3V ± 10%		2.97	3.63	V
V_{IL}	Input LOW Voltage	REF, FB and sOE# Inputs		–	0.8	V
V_{IH}	Input HIGH Voltage			2.0	–	V
V_{IHH}[9]	Input HIGH Voltage	3-Level Inputs (TEST, FS, nF[1:0], PE/HD) (These pins are normally wired to V_{DD},GND or unconected.)		V_{DD} – 0.6	–	V
V_{IMM}[9]	Input MID Voltage			$V_{DD}/2$ – 0.3	$V_{DD}/2$ + 0.3	V
V_{ILL}[9]	Input LOW Voltage			–	0.6	V
I_{IL}	Input Leakage Current	$V_{IN} = V_{DD}/G_{ND}, V_{DD}$ = max. (REF and FB inputs)		–5	5	µA
I_3	3-Level Input DC Current	HIGH, $V_{IN} = V_{DD}$	3-Level Inputs (TEST, FS, nF[1:0], DS[1:0], PD#/DIV, PE/HD)	–	200	µA
		MID, $V_{IN} = V_{DD}/2$		–50	50	µA
		LOW, $V_{IN} = V_{SS}$		–200	–	µA
I_{PU}	Input Pull-up Current	$V_{IN} = V_{SS}$, V_{DD} = max.		–100	–	µA
I_{PD}	Input Pull-down Current	$V_{IN} = V_{DD}$, V_{DD} = max., (sOE#)		–	100	µA
V_{OL}	Output LOW Voltage	I_{OL} = 12 mA (PE/HD = L/H), (nQ[0:1])		–	0.4	V
		I_{OL} = 24 mA (PE/HD = MID), (nQ[0:1])		–	0.4	V
V_{OH}	Output HIGH Voltage	I_{OH} = –12 mA (PE/HD = L/H), (nQ[0:1])		2.4	–	V
		I_{OH} = –24 mA (PE/HD = MID), (nQ[0:1])		2.4	–	V
I_{DDQ}	Quiescent Supply Current	V_{DD} = max., TEST = MID, REF = LOW, sOE# = LOW, outputs not loaded		–	2	mA
I_{DD}	Dynamic Supply Current	At 100 MHz		230		mA
C_{IN}	Input Pin Capacitance			4		pF

AC Test Loads and Waveforms

Figure 2. AC Test Loads

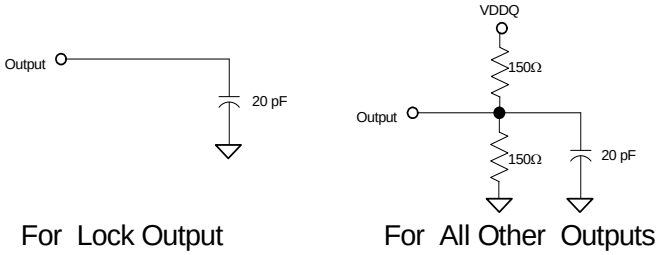
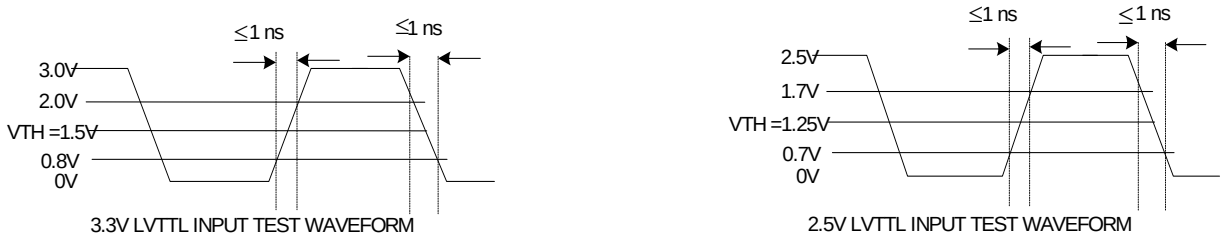


Figure 3. Output Waveforms

Figure 4. Test Waveforms



AC Input Specifications

Parameter	Description	Condition	Min	Max	Unit
T_R,T_F	Input Rise/Fall Time	0.8V – 2.0V	–	10	ns/V
T_{PWC}	Input Clock Pulse	HIGH or LOW	2	–	ns
T_{DCIN}	Input Duty Cycle		10	90	%
F_{REF}	Reference Input Frequency	FS = LOW	6	50	MHz
		FS = MID	12	100	
		FS = HIGH	24	200	

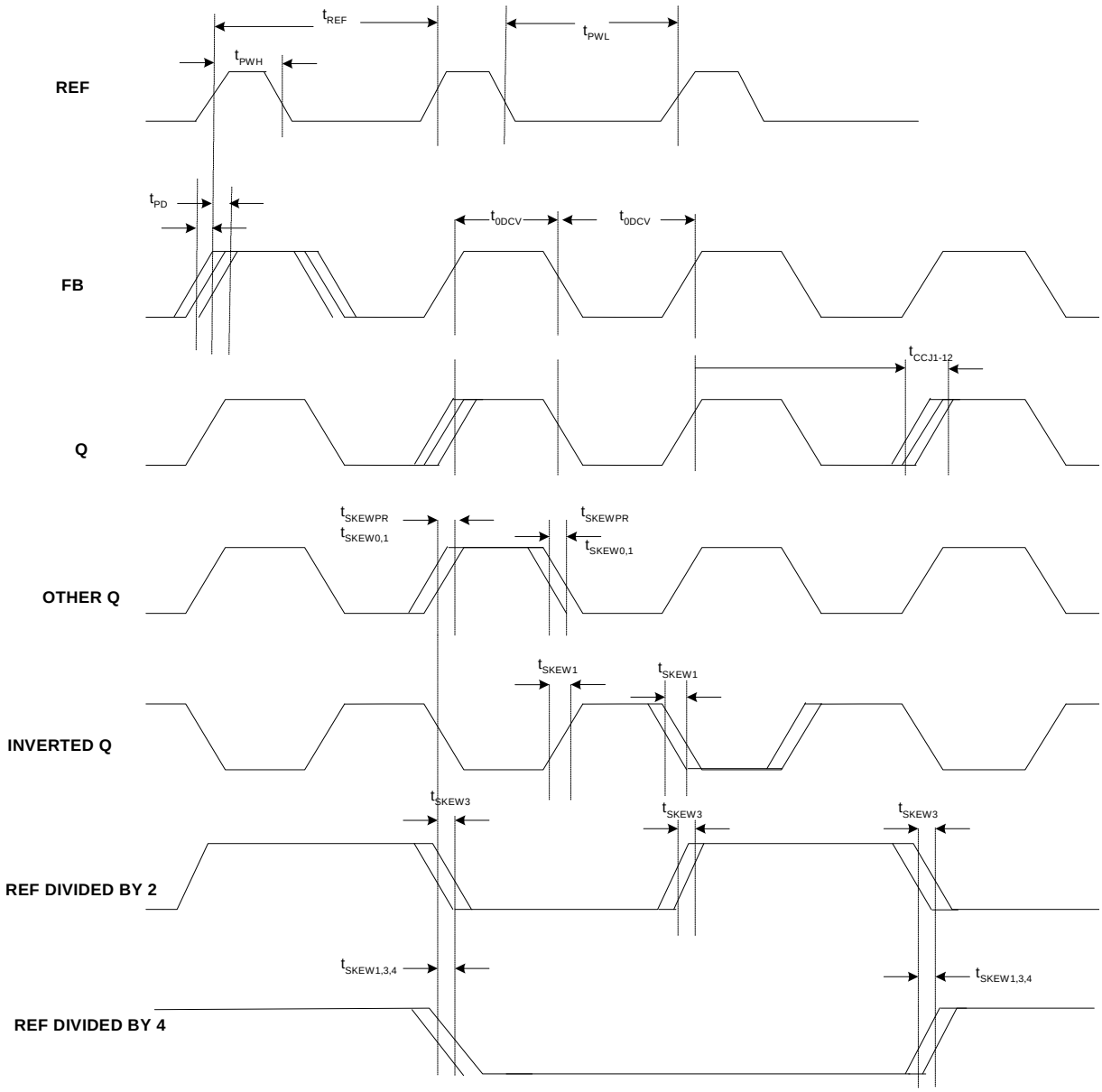
Switching Characteristics

Parameter	Description	Condition	Min	Typ	Max	Unit
F_{OR}	Output Frequency Range		6	–	200	MHz
VCO_{LR}	VCO Lock Range		200	–	400	MHz
VCO_{LBW}	VCO Loop Bandwidth		0.25	–	3.5	MHz
t_{SKEWPR}	Matched-Pair Skew[10]	Skew between the earliest and the latest output transitions within the same bank.	–	50	100	ps
t_{SKEW0}	Output-Output Skew[10]	Skew between the earliest and the latest output transitions among all outputs at $0t_U$.	–	100	200	ps
t_{SKEW1}		Skew between the earliest and the latest output transitions among all outputs for which the same phase delay has been selected.	–	100	200	ps
t_{SKEW2}		Skew between the nominal output rising edge to the inverted output falling edge.	–	–	500	ps
t_{SKEW3}	Output-Output Skew[10]	Skew between non-inverted outputs running at different frequencies.	–	–	500	ps
t_{SKEW4}		Skew between nominal to inverted outputs running at different frequencies.	–	–	500	ps
t_{SKEW5}		Skew between nominal outputs at different power supply levels.	–	–	650	ps
t_{PART}	Part-Part Skew	Skew between the outputs of any two devices under identical settings and conditions (V_{DDQ},V_{DD},temp, air flow, frequency, etc.).	–	–	750	ps
t_{PD0}	Ref-FB Propagation Delay[11]		–250	–	+250	ps
t_{ODCV}	Output Duty Cycle	Fout < 100 MHz, measured at $V_{DD}/2$	48	49.5/ 50.5	52	%
		Fout > 100 MHz, measured at $V_{DD}/2$	45	48/ 52	55	
t_{PWH}	Output High Time Deviation from 50%	Measured at 2.0V for V_{DD} = 3.3V and at 1.7V for V_{DD} = 2.5V.	–	–	1.5	ns
t_{PWL}	Output Low Time Deviation from 50%	Measured at 0.8V for V_{DD} = 3.3V and at 0.7V for V_{DD} = 2.5V.	–	–	2.0	ns
t_R/t_F	Output Rise/Fall Time	Measured at 0.8V – 2.0V for V_{DD} = 3.3V and 0.7V–1.7V for V_{DD} = 2.5V.	0.15	–	1.5	ns
t_{LOCK}	PLL lock time[12,13]		–	–	0.5	ms
t_{CCJ}	Cycle-Cycle Jitter	Divide by one output frequency, FS = L, FB = divide by 1, 2, 4.	–	50	100	ps
		Divide by one output frequency, FS = M/H, FB = divide by 1, 2, 4.	–	70	150	ps

Note
10. Test load = 20 pF, terminated to $V_{CC}/2$. All outputs are equally loaded.
11. t_{PD} is measured at 1.5V for V_{DD} = 3.3V and at 1.25V for V_{DD} = 2.5V with REF rise/fall times of 0.5 ns between 0.8V – 2.0V.
12. t_{LOCK} is the time that is required before outputs synchronize to REF. This specification is valid with stable power supplies which are within normal operating limits.
13. Lock detector circuit may be unreliable for input frequencies lower than 4 MHz, or for input signals which contain significant jitter.

AC Timing Definitions

Figure 5. Timing Definitions

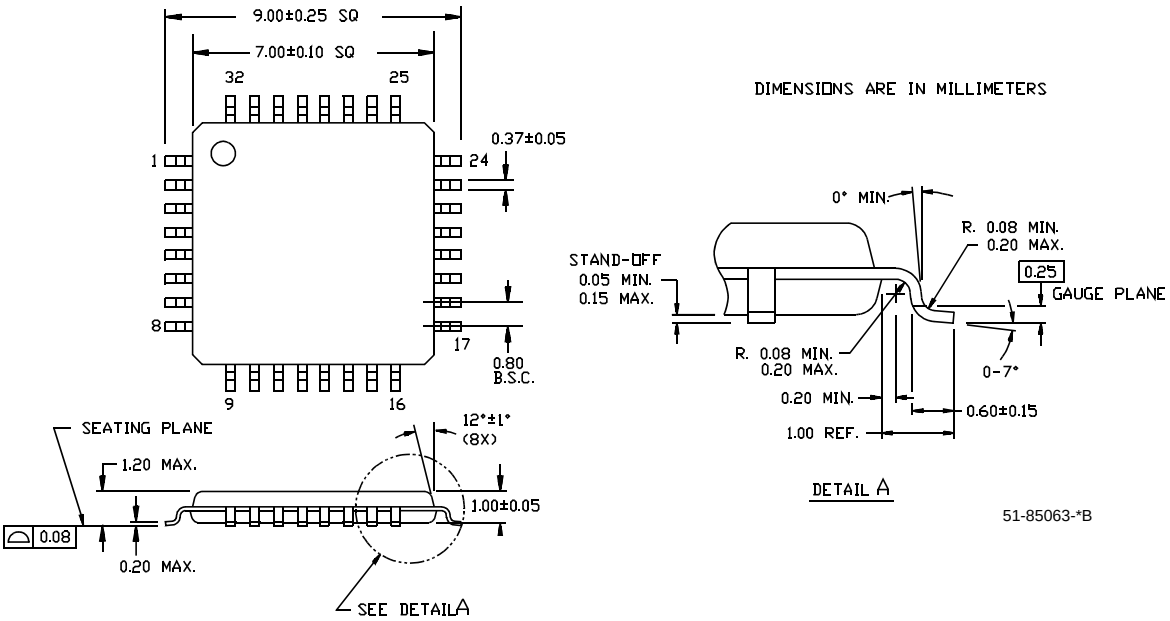


Ordering Information

Part Number	Package Type	Product Flow	Status
CY7B9950AC	32 TQFP	Commercial, 0° to 70°C	Not for new design
CY7B9950ACT	32 TQFP – Tape and Reel	Commercial, 0° to 70°C	Not for new design
CY7B9950AI	32 TQFP	Industrial, –40° to 85°C	Not for new design
CY7B9950AIT	32 TQFP – Tape and Reel	Industrial, –40° to 85°C	Not for new design
Pb-free			
CY7B9950AXC	32 TQFP	Commercial, 0° to 70°C	Active
CY7B9950V-5AXC	32 TQFP	Commercial, 0° to 70°C	Active
CY7B9950AXCT	32 TQFP – Tape and Reel	Commercial, 0° to 70°C	Active
CY7B9950AXI	32 TQFP	Industrial, –40° to 85°C	Active
CY7B9950AXIT	32 TQFP – Tape and Reel	Industrial, –40° to 85°C	Active

Package Drawing and Dimension

Figure 6. 32-lead Thin Plastic Quad Flatpack 7 x 7 x 1.0 mm A32



Document History Page

Document Title: RoboClock® CY7B9950 2.5/3.3V, 200 MHz High-Speed Multi-Phase PLL Clock Buffer Document Number: 38-07338				
Rev.	**ECN No.**	**Issue Date**	**Orig. of Change**	**Description of Change**
**	121663	11/25/02	RGL	New Data Sheet
*A	122548	12/12/02	RGL	Removed the PD#/DIV and DS[1:0] pins in V_{IHH}, V_{IMM} and V_{ILL} for both 2.5V and 3.3V DC Electrical Specs tables
*B	124646	03/05/03	RGL	Corrected the description of Pin 27(TEST) in the Pin Description table Corrected the description of Pin 12 (V_{DDQ}) in the Pin Description table Corrected the Min and Max values of V_{DD} from 2.25/2.75 to 2.375/2.625 Volts in the Absolute Maximum Conditions table
*C	433662	See ECN	RGL	Added Lead-free devices Added Jitter typical values
*D	1562063	See ECN	PYG/AESA	Added Lead-free CY7B9940V-5AXC to Ordering Information Added Status column to Ordering Information table